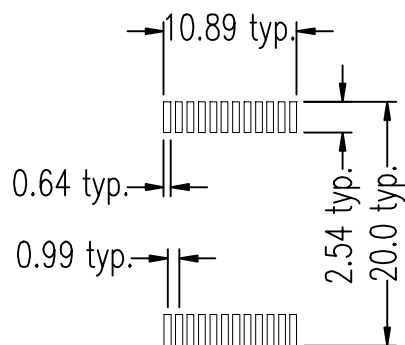
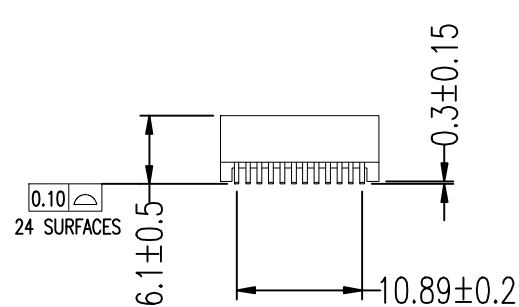
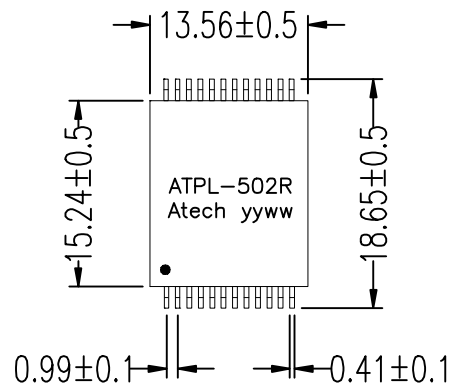
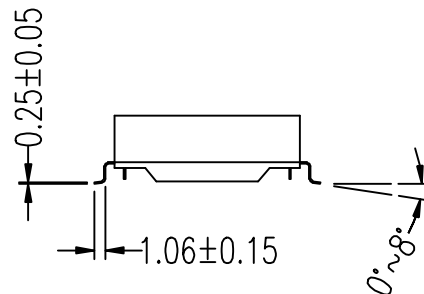


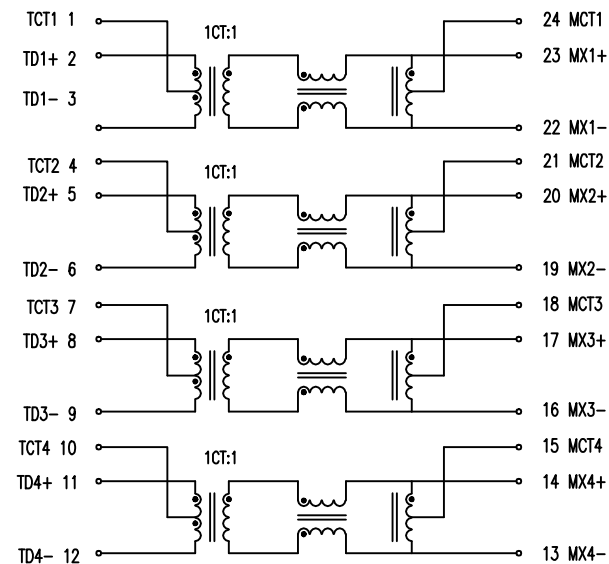


SUGGESTED PAD LAYOUT

TOLERANCES : xx.x0±0.25
0.xx±0.05



UNIT : mm



* RoHS COMPLIANT

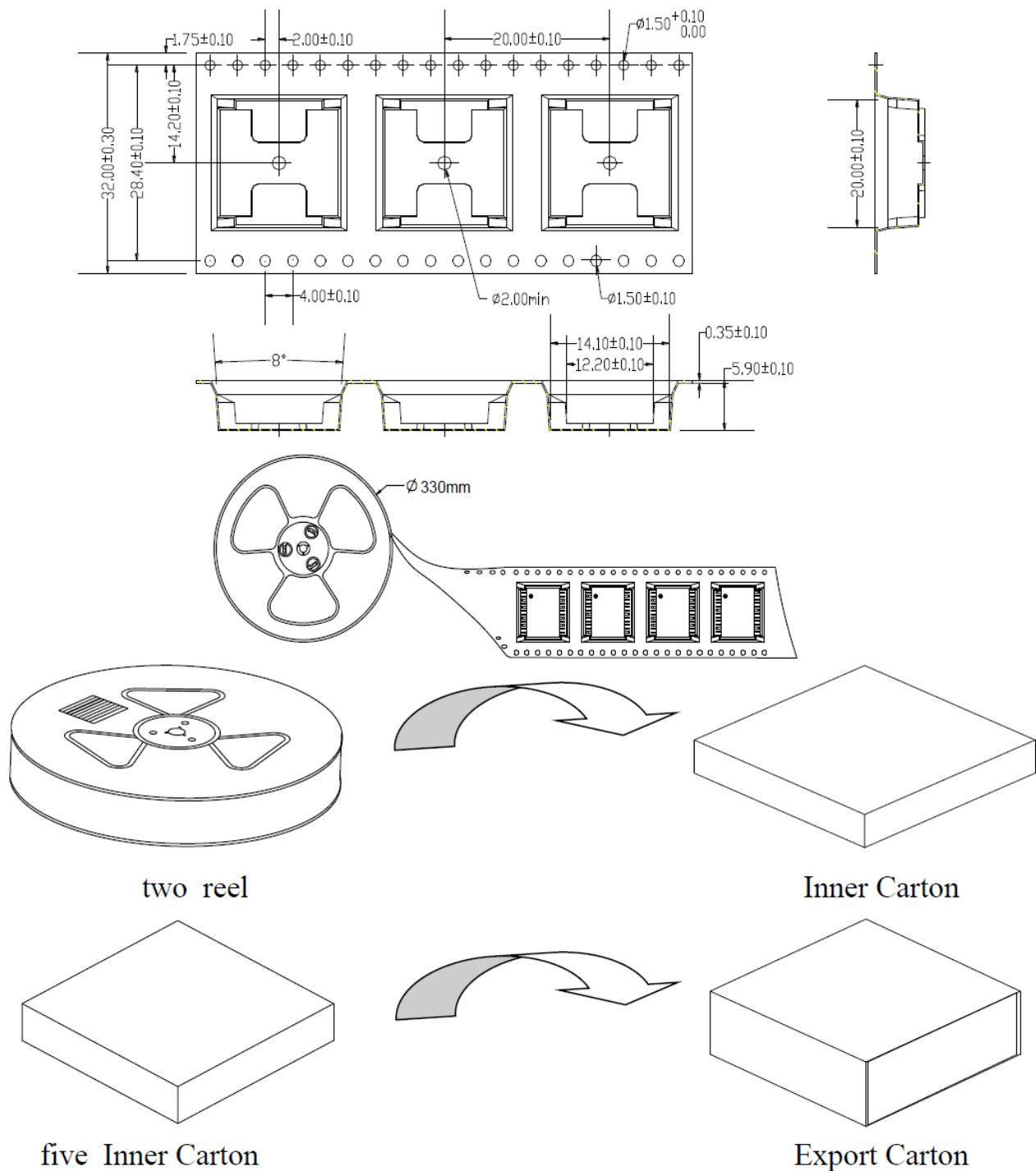
ELECTRICAL CHARACTERISTICS :

1. INSULATION HI-POT : 1500Vrms / 1mA / 60Sec.
2. TURN RATIO (±5%) : 1CT : 1CT
3. OCL : 350uH MIN. 8mA/DC Bias (FROM 0°C TO 70°C)
4. CROSS TALK (dB MIN.) : 1-100MHz = -30dB MIN.
5. INSERTION LOSS (1MHz -100MHz) : -1.1dB MAX.
6. RETURN LOSS (dB MIN. @100Ω) :

1-30MHz	40MHz	50MHz	60-80MHz	100MHz
-18	-14.4	-13.1	-12	-10
7. DIFFERENTIAL TO COMMON MODE REJECTION (dB MIN.) : 1-100MHz = -30dB MIN.
8. OPERATING TEMPERATURE : -40°C~85°C
STORAGE TEMPERATURE : -25°C to +125°C

							TITLE 100/1000 BASE TRANSFORMER	
							DWG. NO. ATPL-502R	
	RELEASE	03/29/2016	SHIRLEY	BETTY	BETTY	UNITS: M/M	SAFETY	
NO:	DESCRIPTION	DATE	BY	CHK	APPD	DATE 03/29/16	P/N:	SHEET 1 OF 1
REVISIONS								DRAW SHIRLEY

Package :



Package Quantity:

One Reel=500Pcs

One Inner Carton=500*2=1000Pcs

One Export Carton=1000*5=5000Pcs

Pb-free Soldering Heat Withstanding Survey

SUGGEST PROFILE



reflow profile

Form-1 (Reference JEDEC J-STD-020D Table 5-2))

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (Tsmax to T _p)	3°C/second max	3°C/second max
Preheat Temperature Min (T _{sm}) Temperature Min (T _{sm}) Time (T _{sm} to T _{sm}) (t _s)	100°C 150°C 60-120seconds	150°C 200°C 60-180seconds
Time maintained above Temperature (T _L) Time (t _L)	183°C 60-150seconds	217°C 60-150seconds
Peak Temperature (T _p)	225°C	260°C
Time within 5°C of actual Peak Temperature (T _p) ²	20 seconds	30 seconds
Ramp-down Rate	6°/second max	6°/second max
Time 25°C to Peak Temperature	6minutes max	8minutes max